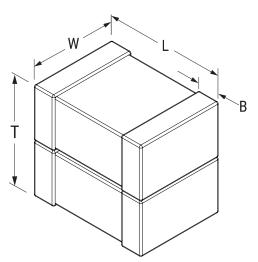




Aliases (C1812X665K1RLC7800) KONNEKT Comm X7R, Ceramic, 6.6 uF, 10%, 100 VDC, X7R



Click here for the 3D model.

| Dimensions | |
|------------|-----------------|
| L | 4.5mm +/-0.4mm |
| W | 3.2mm +/-0.3mm |
| Т | 3.9mm +/-0.4mm |
| В | 0.7mm +/-0.35mm |

| Packaging Specifications | |
|--------------------------|--------------------------|
| Packaging | T&R, 180mm, Plastic Tape |
| Packaging Quantity | 275 |

| General Information | |
|--------------------------|--|
| Series | KONNEKT Comm X7R |
| Style | KONNEKT |
| Description | SMD, MLCC, KONNEKT, Ultra- Stable, Class II |
| Features | High Density Packaging |
| RoHS | Yes |
| Termination | Flexible Termination |
| AEC-Q200 | No |
| Typical Component Weight | 280 mg |
| Chip Size | 1812-2 |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Specifications | |
|--|---------------------|
| Capacitance | 6.6 uF |
| Measurement Condition | 120 Hz 0.5Vrms |
| Tolerance | 10% |
| Voltage DC | 100 VDC |
| Dielectric Withstanding Voltage | 250 VDC |
| Temperature Range | -55/+125°C |
| Temp. Coefficient | X7R |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 15%, 120Hz 0.5Vrms |
| Dissipation Factor | 2.5% 120 Hz 0.5Vrms |
| Aging Rate | 3% Loss/Decade Hour |
| Insulation Resistance | 75.7576 MOhms |

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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